

FIG. 1

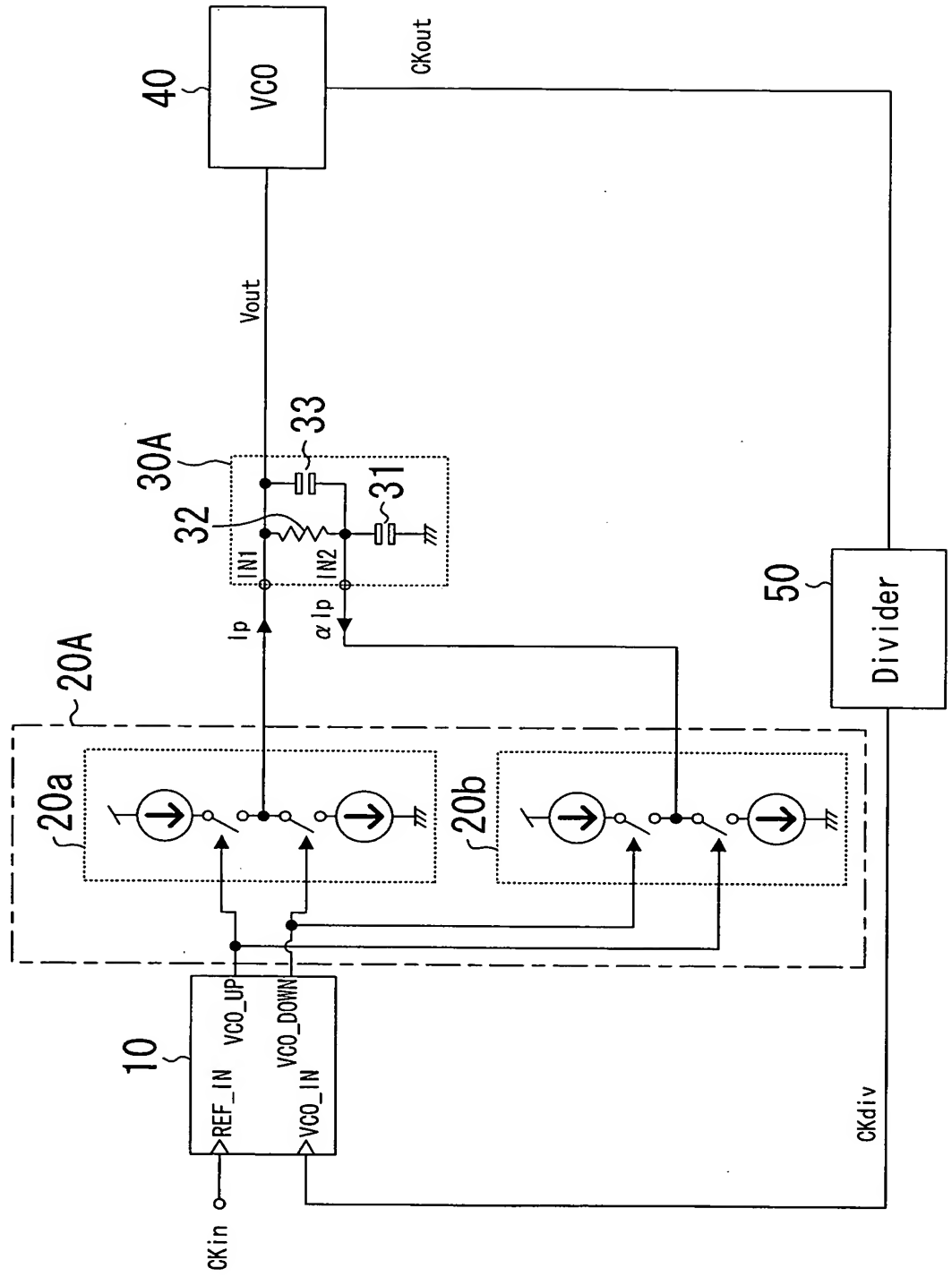
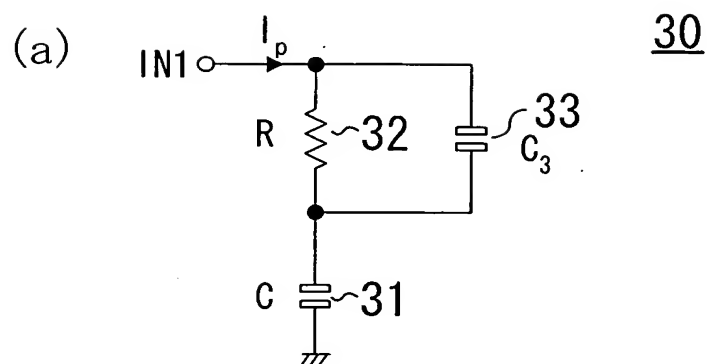
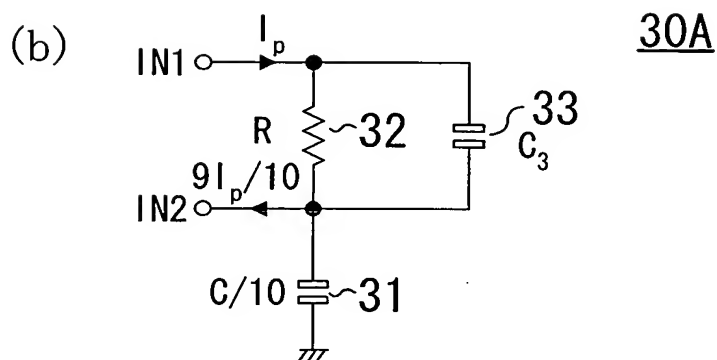


FIG. 2



↕ Equivalent
conversion



↕ Equivalent
conversion

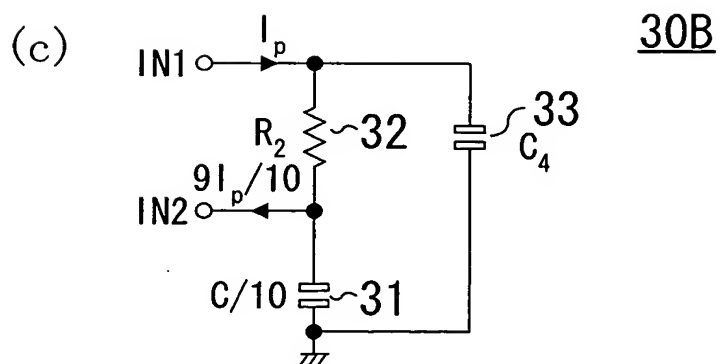


FIG. 3

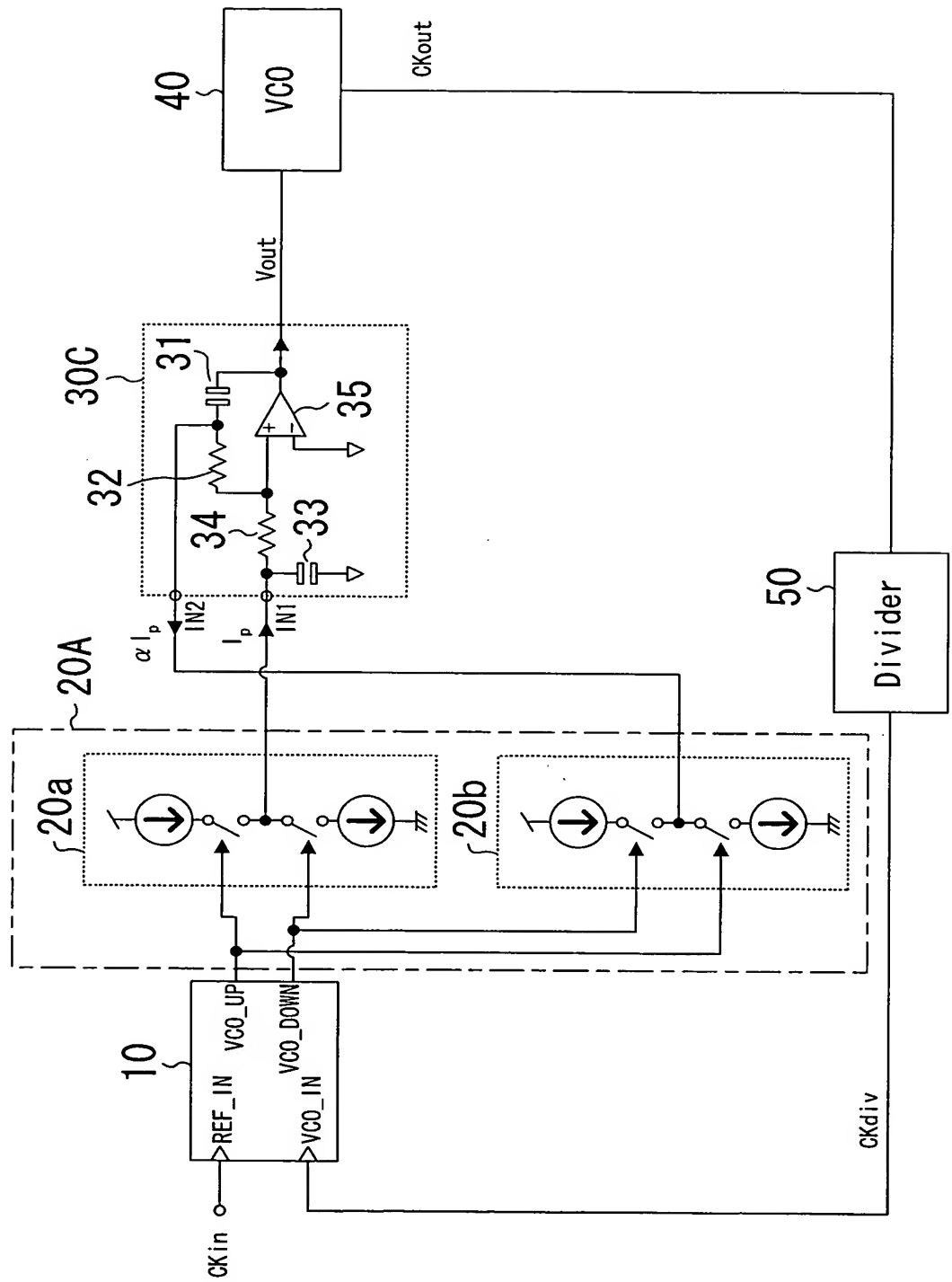
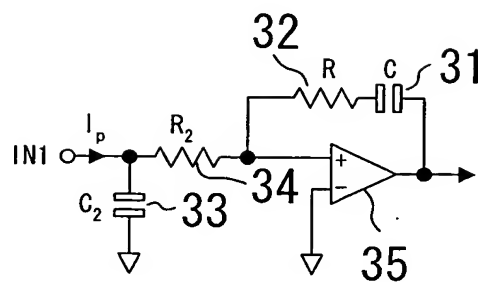


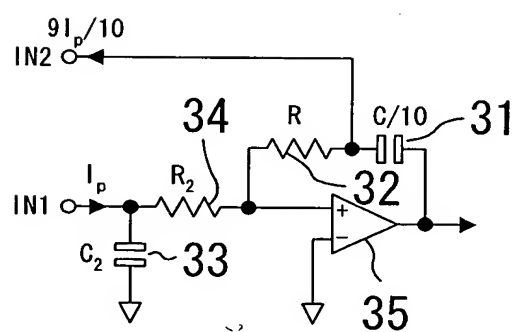
FIG. 4

(a)

30

↕ Equivalent
conversion

(b)

30C

↕ Equivalent
conversion

(c)

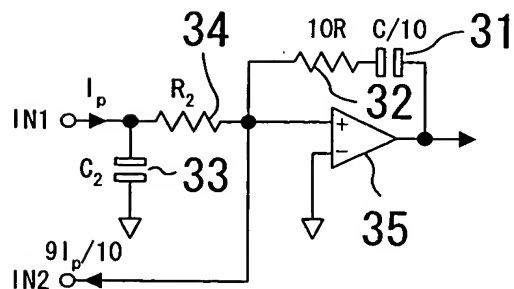
30D

FIG. 5

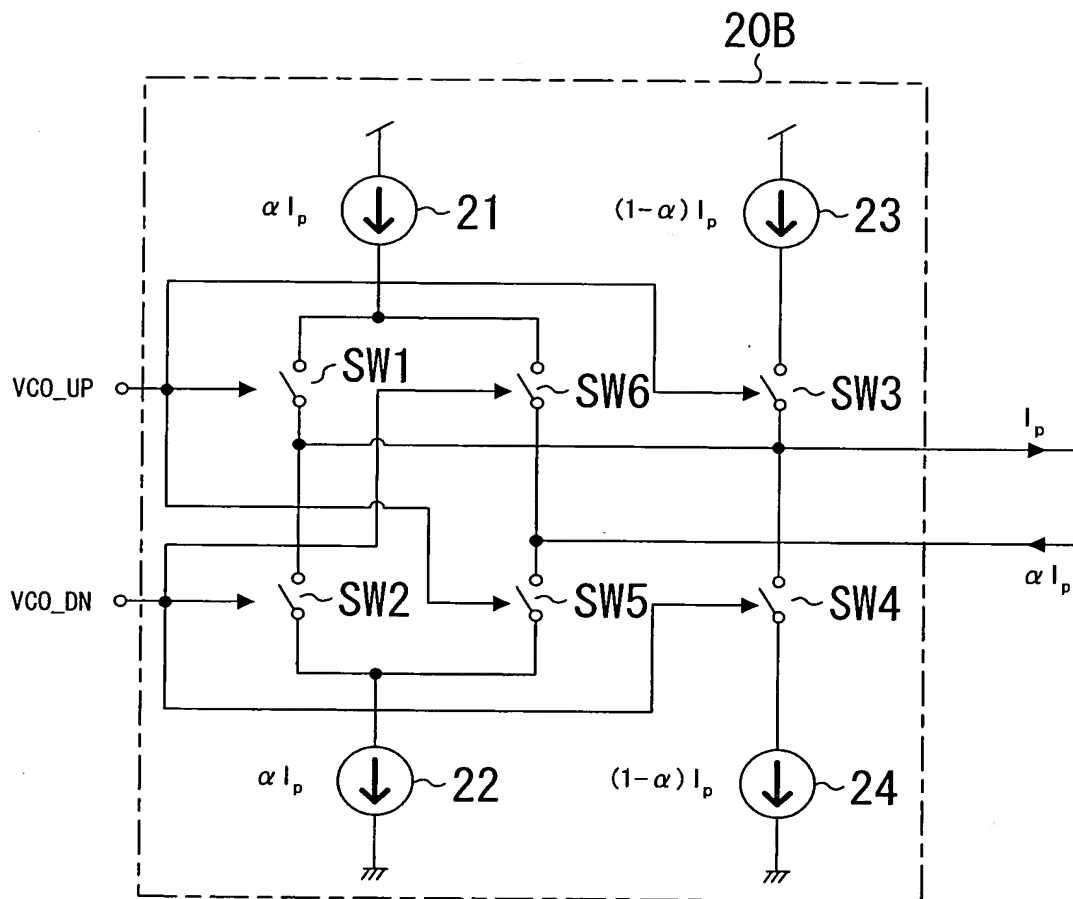


FIG. 6

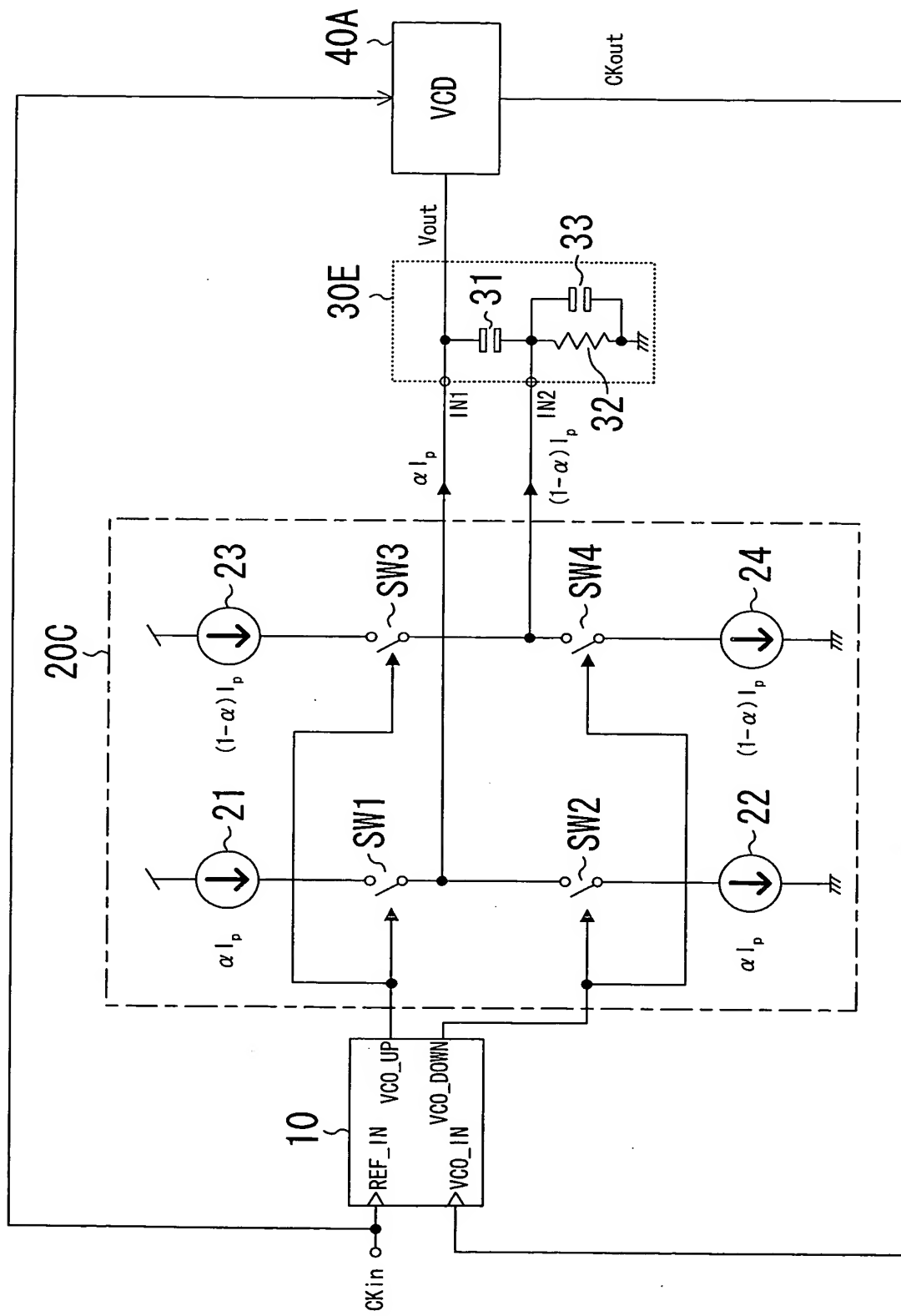
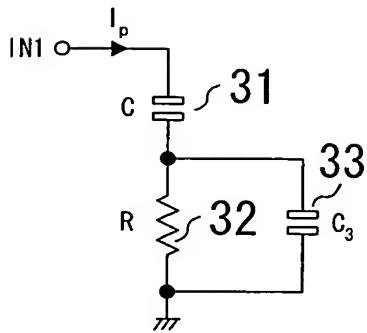


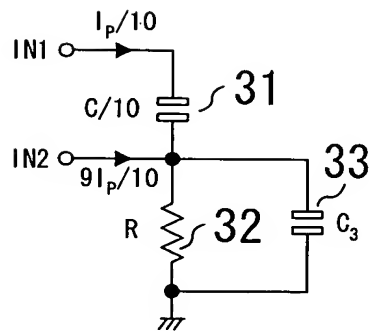
FIG. 7

(a)

30

↕ Equivalent
conversion

(b)

30E

↕ Equivalent
conversion

(c)

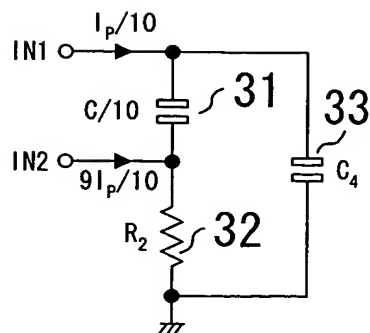
30F

FIG. 8

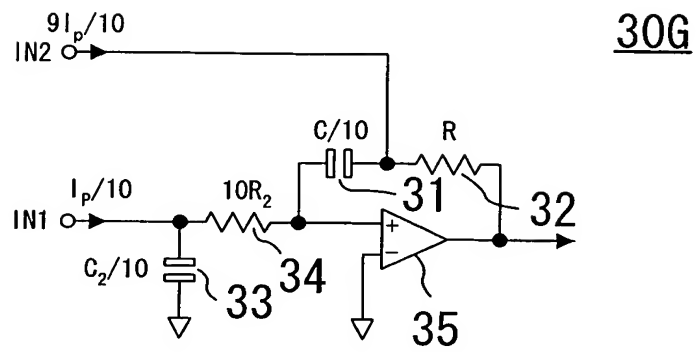
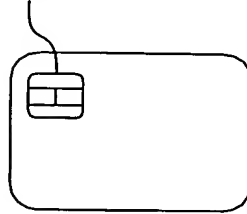


FIG. 9

LSI device incorporating PLL or
DLL of the present invention

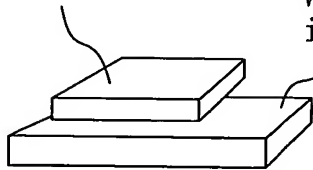


Application to IC card

FIG. 10

COC component
incorporating PLL or DLL
of the present invention

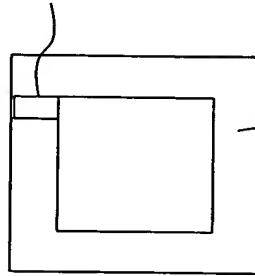
Base material to
which COC component
is attached



Application to COC component

FIG. 11

PLL or DLL of the
present invention

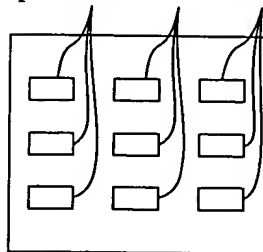


LSI pad region

Installation in LSI pad

FIG. 12

PLL or DLL of the
present invention



Installation in MPU clock

FIG. 13

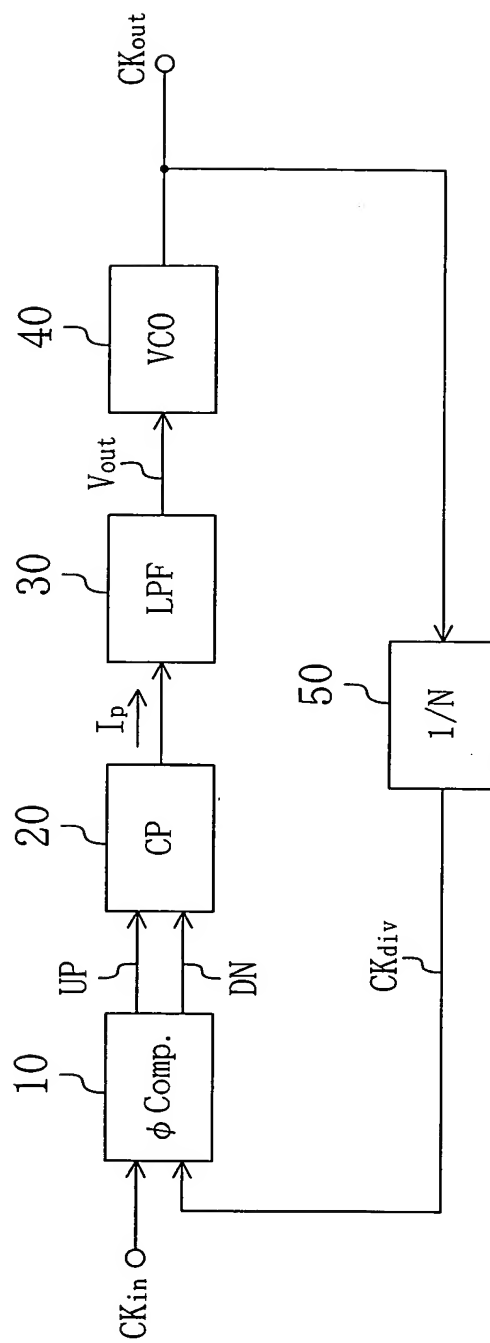


FIG. 14A

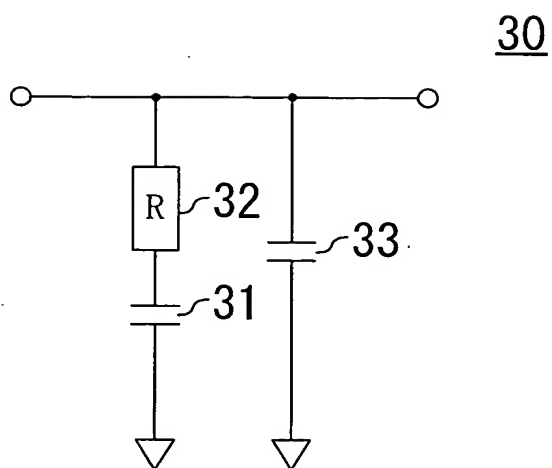


FIG. 14B

